

UHMWPE POROUS MATERIAL

SUNMAP LC-T5320T(SMPLC-T5320T)

Features

- As SUNMAP is a porous sintered material having an open-cell structure; it offers the excellent air and moisture permeability.
- As SUNMAP is made of porous UHMWPE having high wear resistance and low friction coefficient the slip properties of SUNMAP is enhanced.
- SUNMAP offers good chemical resistance against typical acids and alkalis.
- Antistatic
- Flat surface (single side)

Structure

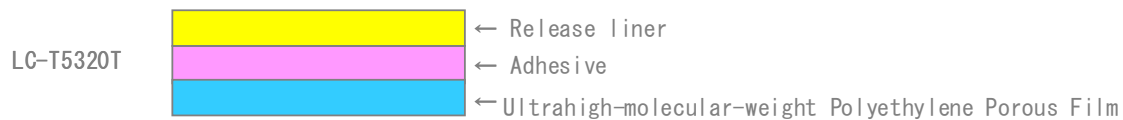


Fig. 1

Properties

Table 1. General Properties

Item	Unit	Characteristic value	Test method
Thickness	mm	0.22	—
Air permeability	cm ³ /cm ² /sec	5	JIS L1096
Pore size	μm	17	—
Porosity	%	30	—
Tensile strength	MPa	12	JIS C2107
Elongation	%	90	JIS C2107
Hardness	Shore D	48	ASTM D2240
Surface Roughness (Ra)	μm	1.2 (Flat surface side)	JIS B 0601
Coefficient of kinetic friction	—	0.1	JIS K7125
Surface resistance	Ω/□	1×10 ¹⁰	JIS K7194

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LC-T5320T_03E
2017.12.4

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Product size

Table 2 Sheet type

Thickness (mm)	Width (mm)	Length (mm)
0.22	450	450

Applications

- In ceramic condenser manufacturing process, SUNMAP is used as “shock-absorber”.
- In LCD manufacturing process, SUNMAP is used as “shock-absorber”.

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